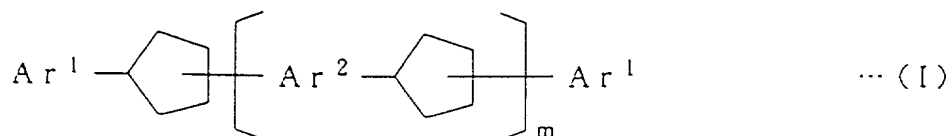


ABSTRACT

This invention provides, as a novel compound suited as an encapsulating material for electronic devices, having a high Tg, being low moisture-absorptive, having a high
 5 adhesion and being rich in fluidity, a cyclopentylene compound represented by Formula (I) and its intermediate cyclopentenyl compound represented by Formula (III). In the formula, m is 0 or more, Ar¹ and Ar² are each a phenol residual group, a naphthol residual group or a fluorene
 10 derivative residual group, and each contain a hydroxyl group or a glycidyloxyl group.



This invention also provides a resin composition and
 15 a molding material which contain the cyclopentylene compound of Formula (I), and an electronic device encapsulated with the molding material.